TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM364461

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
DBD Credit Funding LLC		11/19/2015	LIMITED LIABILITY COMPANY: DELAWARE

RECEIVING PARTY DATA

Name:	Netlist, Inc.
Street Address:	51 Discovery, Suite 150
City:	Irvine
State/Country:	CALIFORNIA
Postal Code:	92618
Entity Type:	CORPORATION: DELAWARE

PROPERTY NUMBERS Total: 7

Property Type	Number	Word Mark
Registration Number:	3502943	N
Registration Number:	3496959	NETLIST
Registration Number:	3624509	NETLIST
Registration Number:	3624502	N
Registration Number:	4120406	HYPERCLOUD
Serial Number:	85739482	HYPERCLOUD, THE LOW LATENCY MEMORY
Registration Number:	4018527	HYPERSTREAM

CH $190.00 3502943

CORRESPONDENCE DATA

Fax Number: 4152687522

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 415-268-7000
Email: ksamia@mofo.com
Correspondent Name: Jennifer Lee Taylor
Address Line 1: 425 Market Street
Address Line 2: Morrison & Foerster LLP
Address Line 4: San Francisco, CALIFORNIA 94105

ATTORNEY DOCKET NUMBER:	63156-1
NAME OF SUBMITTER:	Jennifer Lee Taylor

SIGNATURE:	/JenniferLeeTaylor/
DATE SIGNED:	12/03/2015

Total Attachments: 6
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TERMINATION OF INTELLECTUAL PROPERTY SECURITY AGREEMENT

This Termination of Patent and Trademark Security Agreement, dated as of November 19, 2015 (this "***Termination***"), is executed by DBD Credit Funding LLC ("***Secured Party***"), in favor of Netlist, Inc., a Delaware corporation (the "***Debtor***").

RECITALS

WHEREAS, Debtor and Secured Party entered in a certain Loan and Security Agreement, dated as of July 18, 2013 (the "***Credit Agreement***"); and

WHEREAS, in connection with the Credit Agreement, Debtor and Secured Party entered into a certain Intellectual Property Security Agreement dated as of July 18, 2013 (the "***Security Agreement***"); and

WHEREAS, pursuant to the Security Agreement, Debtor granted to Secured Party a security interest in certain "Collateral" including certain patents and trademarks; and

WHEREAS, the Credit Agreement and the Security Agreement have been terminated.

NOW, THEREFORE, Secured Party agrees as follows:

1. Secured Party is executing and delivering this Termination as further evidence of the termination of the Security Agreement.

2. Secured Party expressly terminates its security interest in the patents and trademarks listed on Exhibit A hereto, which security interest was evidenced by the recordation of the Security Agreement with the United States Patent and Trademark Office on July 18, 2013 in Reel/Frame 030830/0945 (Patents) and in Reel/Frame 5073/0902 (Trademarks).

[signature page follows]

IN WITNESS WHEREOF, this Termination is executed as of the first date written above.

DBD Credit Funding LLC

By: _____
Name: CONSTANTINE M. DAKOLIAS
Title: PRESIDENT

Exhibit A

to Termination of Patent and Trademark Security Agreement

PATENTS

Title	Patent No./ Application Number	Issue/ Application Date
ARRANGEMENT OF INTEGRATED CIRCUITS IN A MEMORY MODULE	6,751,113	15-Jun-2004
ARRANGEMENT OF INTEGRATED CIRCUITS IN A MEMORY MODULE	6,873,534	29-Mar-2005
ARRANGEMENT OF INTEGRATED CIRCUITS IN A MEMORY MODULE	6,930,903	16-Aug-2005
ARRANGEMENT OF INTEGRATED CIRCUITS IN A MEMORY MODULE	6,930,900	16-Aug-2005
HIGH DENSITY MEMORY MODULE USING STACKED PRINTED CIRCUIT BOARDS	7,254,036	7-Aug-2007
HIGH DENSITY MEMORY MODULE USING STACKED PRINTED CIRCUIT BOARDS	7,375,970	20-May-2008
CIRCUIT CARD WITH FLEXIBLE CONNECTION FOR MEMORY MODULE WITH HEAT SPREADER	7,442,050	28-Oct-2008
HIGH DENSITY MODULE HAVING AT LEAST TWO SUBSTRATES AND AT LEAST ONE THERMALLY CONDUCTIVE LAYER THEREBETWEEN	7,630,202	8-Dec-2009
CIRCUIT WITH FLEXIBLE PORTION	7,811,097	12-Oct-2010
MODULE HAVING AT LEAST TWO SURFACES AND AT LEAST ONE THERMALLY CONDUCTIVE LAYER THEREBETWEEN	7,839,645	23-Nov-2010
CIRCUIT WITH FLEXIBLE PORTION	8,033,836	11-Oct-2011
CIRCUIT WITH FLEXIBLE PORTION	8,287,291	16-Oct-2012
MODULE HAVING AT LEAST TWO SURFACES AND AT LEAST ONE THERMALLY CONDUCTIVE LAYER THEREBETWEEN	8,345,427	1-Jan-2013
MODULE HAVING AT LEAST TWO SURFACES AND AT LEAST ONE THERMALLY CONDUCTIVE LAYER THEREBETWEEN	13/731,014	29-Dec-2012
CIRCUIT WITH FLEXIBLE PORTION	13/653254	16-Oct-2012
MEMORY MODULE WITH FLEXIBLE ELECTRICAL CONDUITS AND ELECTRICAL CONNECTORS EXTENDING THROUGH HEAT SPREADER (thin flex)	13/921,159	18-Jun-2013
A Multi-Rank Memory Module	61/682,249	11-Aug-2012
MEMORY BOARD WITH SELF-TESTING CAPABILITY	8,001,434	16-Aug-2011

Title	Patent No./ Application Number	Issue/ Application Date
CIRCUIT PROVIDING LOAD ISOLATION AND NOISE REDUCTION	8,154,901	10-Apr-2012
SYSTEMS AND METHODS FOR REFRESHING A MEMORY MODULE	8,264,903	11-Sep-2012
MEMORY BOARD WITH SELF-TESTING CAPABILITY	8,359,501	22-Jan-2013
SYSTEMS AND METHODS FOR HANDSHAKING WITH A MEMORY MODULE	8,489,837	16-Jul-2013
CIRCUIT PROVIDING LOAD ISOLATION AND NOISE REDUCTION	13/412243	5-Mar-2012
APPARATUS AND METHOD FOR SELF-TEST IN A MULTI-RANK MEMORY MODULE	13/745,790	19-Jan-2013
SYSTEMS AND METHODS FOR REFRESHING A MEMORY MODULE	13/584679	13-Aug-2012
METHOD AND APPARATUS FOR OPTIMIZING DRIVER LOAD IN A MEMORY PACKAGE	13/288850	3-Nov-2011
METHOD OF RESOLVING INTEROPERABILITY ISSUE AMONG MULTIPLE TYPES OF DUAL IN-LINE MEMORY MODULES IN THE SAME MEMORY SUBSYSTEM	13/411,344	2-Mar-2012
MEMORY MODULE WITH DISTRIBUTED DATA BUFFERS AND METHOD OF OPERATION	61/676,883	17-Jul-2012
CIRCUIT FOR MEMORY MODULE	13/287081	1-Nov-2011
SYSTEM AND METHOD UTILIZING DISTRIBUTED BYTE-WISE BUFFERS ON A MEMORY MODULE	99,123,030	13-Jul-2010
ARCHITECTURE FOR MEMORY MODULE WITH PACKAGES OF THREE-DIMENSIONAL STACKED (3DS) MEMORY CHIPS	201080039043.0	12-Mar-12
ARCHITECTURE FOR MEMORY MODULE WITH PACKAGES OF THREE-DIMENSIONAL STACKED (3DS) MEMORY CHIPS	10730021.2	7-Feb-12
ARCHITECTURE FOR MEMORY MODULE WITH PACKAGES OF THREE-DIMENSIONAL STACKED (3DS) MEMORY CHIPS	2012-520662	13-Jan-12
ARCHITECTURE FOR MEMORY MODULE WITH PACKAGES OF THREE-DIMENSIONAL STACKED (3DS) MEMORY CHIPS	2012-7004038	15-Feb-12
HIGH-DENSITY MEMORY MODULE UTILIZING LOW-DENSITY MEMORY COMPONENTS	7,286,436	23-Oct-2007
MEMORY MODULE DECODER	7,289,386	30-Oct-2007
MEMORY MODULE WITH A CIRCUIT PROVIDING LOAD ISOLATION AND MEMORY DOMAIN TRANSLATION	7,532,537	12-May-2009
MEMORY MODULE DECODER	7,619,912	17-Nov-2009

Title	Patent No./ Application Number	Issue/ Application Date
MEMORY MODULE WITH A CIRCUIT PROVIDING LOAD ISOLATION AND MEMORY DOMAIN TRANSLATION	7,636,274	22-Dec-2009
MEMORY MODULE DECODER	7,864,627	4-Jan-2011
CIRCUIT PROVIDING LOAD ISOLATION AND MEMORY DOMAIN TRANSLATION FOR MEMORY MODULE	7,881,150	1-Feb-2011
CIRCUIT PROVIDING LOAD ISOLATION AND MEMORY DOMAIN TRANSLATION FOR MEMORY MODULE	7,916,574	29-Mar-2011
CIRCUIT PROVIDING LOAD ISOLATION AND MEMORY DOMAIN TRANSLATION FOR MEMORY MODULE	8,072,837	6-Dec-2011
CIRCUIT FOR PROVIDING CHIP-SELECT SIGNALS TO A PLURALITY OF RANKS OF A DDR MEMORY MODULE	8,081,535	20-Dec-2011
CIRCUIT FOR PROVIDING CHIP-SELECT SIGNALS TO A PLURALITY OF RANKS OF A DDR MEMORY MODULE	8,081,537	20-Dec-2011
CIRCUIT FOR MEMORY MODULE	8,081,536	20-Dec-2011
SYSTEM AND METHOD OF INCREASING ADDRESSABLE MEMORY SPACE ON A MEMORY BOARD	12/504131	16-Jul-2009
CIRCUIT FOR PROVIDING CHIP-SELECT SIGNALS TO A PLURALITY OF RANKS OF A DDR MEMORY MODULE	13/287042	1-Nov-2011
SYSTEM AND METHOD UTILIZING DISTRIBUTED BYTE-WISE BUFFERS ON A MEMORY MODULE	12/761179	15-Apr-2010
HEAT SPREADER FOR ELECTRONIC MODULES	7,619,893	17-Nov-2009
HEAT SPREADER FOR MEMORY MODULES	7,839,643	23-Nov-2010
HEAT DISSIPATION FOR ELECTRONIC MODULES	8,018,723	13-Sep-2011
MEMORY MODULE HAVING THERMAL CONDUITS	8,488,325	16-Jul-2013
HEAT DISSIPATION FOR ELECTRONIC MODULES	13/205477	8-Aug-2011

Exhibit B

to Termination of Patent and Trademark Security Agreement

TRADEMARKS

Mark	Registration/ Serial Number	Registration/ Application Date
N (DESIGN)	3502943	September 16, 2008
NETLIST	3496959	September 2, 2008
NETLIST	3624509	May 19, 2009
N (DESIGN)	3624502	May 19, 2009
HYPERCLOUD	4120406	April 3, 2012
HyperCloud, the low latency memory	85739482	September 26, 2012
HYPERSTREAM	4018527	August 30, 2011